WHAT IS CLAIMED IS:

1. A heat-sensitive stencil comprising a porous resin layer, and a resin film laminated on said porous resin layer, and a thin resin layer interposed between said porous resin layer and said porous resin layer.

2. A heat-sensitive stencil as set forth in claim 1, wherein said resin film is thermoplastic.

3. A heat-sensitive stencil as set forth in claim 1, wherein said thin resin layer has at least one resin component which is the same as that of said porous resin layer.

4. A heat-sensitive stencil as set forth in claim 1, wherein said thin resin layer has no resin component which is common to that of said porous resin layer.

5. A heat-sensitive stencil as set forth in claim 1, wherein said thin resin layer and said porous resin layer form a continuous unitary body.

6. A heat-sensitive stencil as set forth in claim 1, further comprising a non-resinous porous layer formed on said porous resin layer.

7. A heat-sensitive stencil as set forth in claim 1, and having a flexural rigidity of 20-40 mN.

8. A heat-sensitive stencil as set forth in claim 1, and wound around a cylindrical core.

9. A heat-sensitive stencil as set forth in claim 1, and provided with imagewise perforations.

10. A heat-sensitive stencil as set forth in claim 1, and providing air permeability of 2.0 $cm^3/cm^2 \cdot sec$ to 160 $cm^3/cm^2 \cdot sec$ when perforated to have an open ratio of at least 20 %.

11. A heat-sensitive stencil as set forth in claim 1, wherein said perforations are thermally formed.

12. A stencil printer having a stencil as set forth in claim 9.

13. A method of preparing a heat-sensitive stencil as set forth in claim 5, comprising the steps of:

applying a coating composition to a surface of a resin film, said composition containing a resin, a first solvent capable of dissolving said resin, and a second solvent substantially incapable of dissolving said resin; and

drying said applied composition to form said thin resin layer and said porous layer on said surface of said film.

14. A method as set forth in claim 5, wherein the weight ratio of said first resin to said second resin is greater than 1:1.

15. A method of preparing a heat-sensitive stencil as set forth in claim 1, comprising the steps of:

applying a first coating composition to a surface of a resin film,

drying said applied first composition to form said thin resin layer on said surface of said film,

applying a second coating composition to a surface of said thin resin layer, and

drying said applied second composition to form said porous resin layer on said surface of said thin resin layer.

16. A material for forming a stencil, comprising a thin resin layer, and a porous resin layer formed on said resin layer.

17. A heat-sensitive stencil comprising a resin film having provided thereon a material according to claim 16.